

# SANYO Semiconductors DATA SHEET

An ON Semiconductor Company

# LC709006A — I/O-Expander for Microcontroller

#### Overview

The LC709006A is a peripheral IC dedicated for expanding the capability of the microcontroller (MCU) I/O ports. It interfaces with the microcontroller through synchronous serial communication. Communication with the extended I/O ports is accomplished through 24-bit parallel I/O. The extended port features include the capabilities to specify the I/O direction on a bit basis, to specify the output type (CMOS or N-channel open drain), and to specify the I/O voltage level on a port basis according to the power level of the peripheral equipment. These features make allow the LC709004A to be used in a wide variety of applications.

#### **Features**

- 4-/5-wire synchronous serial transmission and reception, and 24-bit parallel I/O
- Wide operating voltage range (2.0V to 6.0V)
- Multifunction I/O ports
  - I/O direction specification: Bit units
  - CMOS or Nch-OD output type specification: Bit units
  - Output voltage adjustment: Port (8 bits) units
- Output current: 12mA max. (capable of driving a green LED directly)
- Data transmission and reception: Can control reception of input data and transmission of output data in parallel.
- Cascaded configuration: Ports can be expanded in units of 24 bits × n (n is the number of LSI chips).
- Packaging from: MFP36SDJ (375mil): lead-free type

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http://www.sanyosemi.com/en/network/

# **Specifications**

Absolute Maximum Ratings at  $Ta=25^{\circ}C,\ V_{SS}=V_{SS}\ P0=V_{SS}P2=0V$ 

Darameter	Cumbal	Din/Domorko	Conditions			Ratings		Llois
Parameter	Symbol	Pin/Remarks	Conditions	V <sub>DD</sub> [V]	min	typ	max	Unit
Maximum supply voltage	V <sub>DD</sub> max	V <sub>DD</sub> , V <sub>DD</sub> P0, V <sub>DD</sub> P1, V <sub>DD</sub> P2	$V_{DD}=V_{DD}P0=$ $V_{DD}P1=V_{DD}P2$		-0.3		+7.0	
Input voltage	VI	RES, CS, DIN,			-0.3		V <sub>DD</sub> +0.3	
Output voltage	V <sub>O</sub>	DOUT			-0.3		V <sub>DD</sub> +0.3	
Input/output voltage	V <sub>IO</sub> (1)	Port 0			-0.3		V <sub>DD</sub> P0 +0.3	V
	V <sub>IO</sub> (2)	Port 1			-0.3		V <sub>DD</sub> P1 +0.3	
	V <sub>IO</sub> (3)	Port 2			-0.3		V <sub>DD</sub> P2 +0.3	
High level output current								
Peak output current	IOPH(1)	Ports 0 to 2	CMOS output		-7			
	IOPH(2)	DOUT	selected Per 1 applicable pin		-13			
Mean output current	IOMH(1)	Ports 0 to 2	CMOS output		-3			
(Note 1)	IOMH(2)	DOUT	selected Per 1 applicable pin		-6			
Total output current	∑IOP0H	Port 0	Total of all applicable pins		-32			mA
	∑IOP1H	Port 1	Total of all applicable pins		-32			
	∑IOP2H	Port 2	Total of all applicable pins		-32			
	∑IOAH	DOUT, ports 0 to 1	Total of all applicable pins		-105			
Low level output current								
Peak output current	IOPL(1)	Ports 0 to 2	Per 1 applicable				16	
	IOPL(2)	DOUT	pin				13	
Mean output current	IOML(1)	ports 0 to 2	Per 1 applicable				7	
(Note 1)	IOML(2)	DOUT	pin				6	
Total output current	∑IOP0L	Port 0	Total of all applicable pins				32	mA
	∑IOP1L	Port 1	Total of all applicable pins				32	
	∑IOP2L	Port 2	Total of all applicable pins				32	
	ΣIOAL	DOUT, ports 0 to 2	Total of all applicable pins				105	
Power dissipation	Pd max	MFP36SDJ	Ta=-30 to +70°C				330	
			Ta=-40 to +85°C				250	mW
Operating temperature	Topr				-40		85	°C
Storage temperature	Tstg				-55		125	

Note 1: The mean output current is a mean value measured over 100ms.

# Allowable Operating Conditions at $Ta=-40\ to\ +85^{\circ}C,\ V_{SS}=V_{SS}\ P0=V_{SS}P2=0V$

D	0	D: /D	0 - 100		Spec	cification (No	ote 3)	Unit	
Parameter	Symbol	Pin/Remarks	Conditions	V <sub>DD</sub> [V]	V <sub>DD</sub> [V] min typ		max	Uill	
Operating supply voltage	V <sub>DD</sub> (1)	$V_{DD}$			2.0		6.0		
	V <sub>DD</sub> (2)	V <sub>DD</sub> P0	Supply voltage must be within V <sub>DD</sub> (1)'s specification.		V <sub>DD</sub> -3.0		V <sub>DD</sub>		
	V <sub>DD</sub> (3)	V <sub>DD</sub> P1, V <sub>DD</sub> P2	Supply voltage must be within V <sub>DD</sub> (1)'s specification.		V <sub>DD</sub>		V <sub>DD</sub> +3.0		
High level input voltage	V <sub>IH</sub> (1)	DIN, ports 0 to 2		4.5 to 6.0	0.3V <sub>DD</sub> +0.7		$V_{DD}Px$	V	
	V <sub>IH</sub> (2)	DIN, ports 0 to 2		2.0 to 6.0	0.3V <sub>DD</sub> +0.7		$V_{DD}Px$	V	
	V <sub>IH</sub> (3)	RES, CS, CLK		4.5 to 6.0	0.4V <sub>DD</sub> +0.7		V <sub>DD</sub>		
	V <sub>IH</sub> (4)	RES, CS, CLK		2.0 to 6.0	0.4V <sub>DD</sub> +0.7		V <sub>DD</sub>		
Low level input voltage	V <sub>IL</sub> (1)	DIN, ports 0 to 2		4.5 to 6.0	V <sub>SS</sub>		0.2V <sub>DD</sub> +0.1		
	V <sub>IL</sub> (2)	DIN, ports 0 to 2		2.0 to 6.0	V <sub>SS</sub>		0.2V <sub>DD</sub> +0.1		
	V <sub>IL</sub> (3)	RES, CS, CLK		4.5 to 6.0	V <sub>SS</sub>		0.1V <sub>DD</sub> +0.2		
	V <sub>IL</sub> (4)	RES, CS, CLK		2.0 to 6.0	V <sub>SS</sub>		0.1V <sub>DD</sub> +0.2		

Note 3: V<sub>DD</sub>Px denote the power supply pin (V<sub>DD</sub>P0,V<sub>DD</sub>P1,V<sub>DD</sub>P2) for port pins.

# **Electrical Characteristics** at Ta = -40 to $+85^{\circ}C$ , $V_{SS} = V_{SS}$ $P0 = V_{SS}$ P2 = 0V

Danasatas	O: male al	Dia/Damanta	0	(No	te 3)	Spe	cification		1.1-24
Parameter	Symbol	Pin/Remarks	Conditions	V <sub>DD</sub> [V]	V <sub>DD</sub> Px[V]	min	typ	max	Unit
High level input current	lН	RES, CS, CLK, Ports 0 to 2	V <sub>IN</sub> =V <sub>DD</sub> (including output Tr. off leakage current)	2.0 to 6.0				10	
Lower level input current	ημ	RES, CS, CLK, Ports 0 to 2	VIN=VSS (including output Tr. off leakage current)	2.0 to 6.0		-10			μА
High level output	V <sub>OH</sub> (1)	Ports 0	I <sub>OH</sub> =-2mA	2.0 to 6.0	4.5 to 6.0	V <sub>DD</sub> Px-0.5			
voltage	V <sub>OH</sub> (2)		I <sub>OH</sub> =-5mA	2.0 to 6.0	4.5 to 6.0	V <sub>DD</sub> Px-1.0			
	V <sub>OH</sub> (3)		I <sub>OH</sub> =-1mA	2.0 to 6.0	2.0 to 6.0	V <sub>DD</sub> Px-0.5			
	V <sub>OH</sub> (4)	Ports 1	I <sub>OH</sub> =-2mA	2.0 to 6.0	4.5 to 6.0	V <sub>DD</sub> Px-0.5			
	V <sub>OH</sub> (5)		I <sub>OH</sub> =-5mA	2.0 to 6.0	4.5 to 6.0	V <sub>DD</sub> Px-1.0			
	V <sub>OH</sub> (6)		I <sub>OH</sub> =-1mA	2.0 to 6.0	2.0 to 6.0	V <sub>DD</sub> Px-0.5			
	V <sub>OH</sub> (7)	DOUT	I <sub>OH</sub> =-5mA	4.5 to 6.0		V <sub>DD</sub> Px-0.5			
	V <sub>OH</sub> (8)		I <sub>OH</sub> =-10mA	4.5 to 6.0		V <sub>DD</sub> Px-1.0			
	V <sub>OH</sub> (9)		I <sub>OH</sub> =-2mA	2.0 to 6.0		V <sub>DD</sub> Px-0.5			
Lower level output	V <sub>OL</sub> (1)	Ports 0	I <sub>OL</sub> =5mA	4.5 to 6.0	2.0 to 6.0			0.4	V
voltage	V <sub>OL</sub> (2)	1	I <sub>OL</sub> =12mA	4.5 to 6.0	2.0 to 6.0			1	
	V <sub>OL</sub> (3)		I <sub>OL</sub> =2mA	2.0 to 6.0	2.0 to 6.0			0.4	
	V <sub>OL</sub> (4)	Ports 1,2	I <sub>OL</sub> =5mA	4.5 to 6.0	4.5 to 6.0			0.4	
	V <sub>OL</sub> (5)		I <sub>OL</sub> =12mA	4.5 to 6.0	4.5 to 6.0			1	
	V <sub>OL</sub> (6)		I <sub>OL</sub> =2mA	2.0 to 6.0	2.0 to 6.0			0.4	
	V <sub>OL</sub> (7)	DOUT	I <sub>OL</sub> =5mA	4.5 to 6.0				0.4	
	V <sub>OL</sub> (8)		I <sub>OL</sub> =10mA	4.5 to 6.0				1	
	V <sub>OL</sub> (9)		I <sub>OL</sub> =2mA	2.0 to 6.0				0.4	
Pull-up resistance	Rpu(1)	CS	V <sub>OH</sub> =V <sub>SS</sub>	4.5 to 6.0		100	230	650	kΩ
Voltage hysteresis	VHIS	RES, CS, CLK		2.0 to 6.0			0.1V <sub>DD</sub>		V
Consumption current (operation stopped)	IDDSP	V <sub>DD</sub> =V <sub>DD</sub> P0= V <sub>DD</sub> P1=V <sub>DD</sub> P2	RES=CS=VDD  CLK=DIN=VDD or VSS  DOUT=open P0 to P2=open or VDD  or VSS (Note 2)	2.0 to 6.0				20	μА
Pin capacity	CP	All pins	Other than test pin VIN=VSS f=1MHz Ta=25°C	2.0 to 6.0			10		pF

Note 2: The consumption current does not include the current flowing into the port's output transistor.

Note 3:  $V_{DD}Px$  denote the power supply pin  $(V_{DD}P0, V_{DD}P1, V_{DD}P2)$  for port pins.

# $\textbf{Switching I/O Characteristics} \text{ at } Ta=-40 \text{ to } +85^{\circ}\text{C}, V_{DD}=V_{DD}P0=V_{DD}P1=V_{DD}P2, V_{SS}=V_{SS}P0=V_{SS}P1=V_{SS}P2, V_{SS}=0V_{SS}P1=V_{SS}P2, V_{SS}=0V_{SS}P1=V_{SS}P$

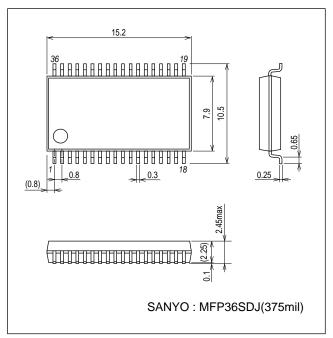
Parameter	Symbol	Pin/Remarks	Conditions			pecification		Unit
	-,			V <sub>DD</sub> [V]	min	typ	max	
Clock setup time	TsCLK	CS, CLK	<ul> <li>Specified with</li> </ul>					
			respect to falling	2.0 to 6.0	100			
			edge of $\overline{\text{CS}}$ .					
			•See Fig. 9.					
Chip select low level setup	TsICS	CS, CLK	•Specified with					
time			respect to falling	2.0 to 6.0	100			
			edge of CS.					
		<del></del>	•See Fig. 9.					
Chip select low level hold	ThICS	CS, CLK	<ul> <li>Specified with</li> </ul>					
time			respect to falling	2.0 to 6.0	100			
			edge of $\overline{\text{CS}}$ .					
			•See Fig. 9.					
Clock hold time	ThCLK	CS, CLK	<ul> <li>Specified with</li> </ul>					
			respect to falling	2.0 to 6.0	200			
			edge of CS.	2.0 10 0.0	200			
			∙See Fig. 9.					
Clock low level pulse width	TwlCLK	CLK	∙See Fig. 9.	4.5 to 6.0	250			
				2.7 to 6.0	500			
				2.0 to 6.0	1000			
Clock high level pulse	TwhCLK	CLK	•See Fig. 9.	4.5 to 6.0	250			
width				2.7 to 6.0	500			
				2.0 to 6.0	1000			
Chip select high level setup time	TshCS	CS, RES	•See Fig. 9.	2.0 to 6.0	200			
Chip select high level hold	ThhCS	CS, RES	•See Fig. 9.	001.00	400			
time				2.0 to 6.0	100			ns
Chip select low level pulse width	TwlCS	CS, RES	•See Fig. 9.	2.0 to 6.0	200			113
Reset low level pulse width	TwiRES	CS, RES	•See Fig. 9.	2.0 to 6.0	150			
Data setup time	TsDIN	DIN	•Specified with	4.5 to 6.0	30			
			respect to falling	4.5 10 6.0	30			
			edge of CLK. •See Fig. 9.	2.0 to 6.0	50			
Data hold time	ThDIN	DIN	Specified with	4.5 to 6.0	50			
			respect to falling edge of CLK.	2.7 to 6.0	150			
			•See Fig. 9.	2.0 to 6.0	300			
Serial data output delay	TdD0UT	DOUT	•Specified with	4.5 to 6.0			200	
time			respect to falling	2.7 to 6.0			400	
(Note 4)			edge of CLK. •See Fig. 9.	2.0 to 6.0			800	
Port data output delay time	TdPOUT	Port 0 to 2	Specified with	4.5 to 6.0			200	
			respect to rising	2.7 to 6.0			400	
			edge of CS.					
			•See Fig. 9.	2.0 to 6.0			800	
Port data input setup time	TsPIN	Port 0 to 2	•Specified with respect to rising	4.5 to 6.0	30			
			edge of CLK. •See Fig. 9.	2.0 to 6.0	50			
Port data input hold time	ThPIN	Port 0 to 2	•Specified with	4.5 to 6.0	50			
			respect to rising edge of CLK.	2.7 to 6.0	150			
	i	1	Leage of CLK	1				i

Note 4: The input data of P00 will be out from DOUT terminal at the first negative edge of  $\overline{\text{CLK}}$  signal. Because of this, Serial data output delay time of the first clock will be the time measured from the negative edge of the  $\overline{\text{CLK}}$  or the time at the input data (P00) is settled.

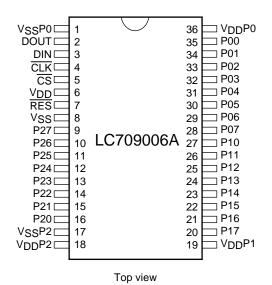
# **Package Dimensions**

unit: mm (typ)

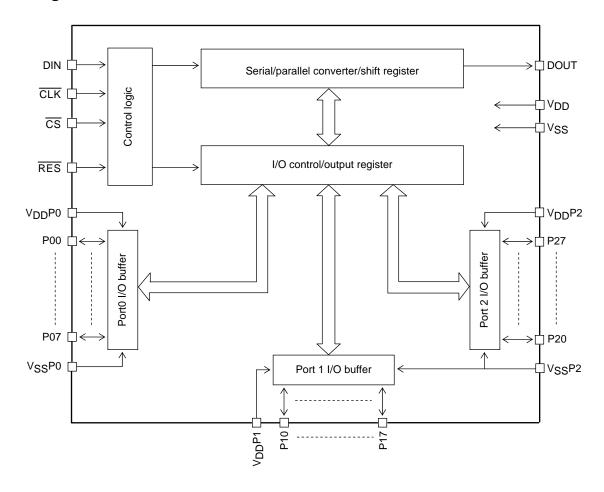
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# **Pin Assignment**



# **Block Diagram**



## **Pin Description**

Pin Name	I/O	Description	I/O Type	Reset Time
V <sub>SS</sub>	-	• - power supply pin		
V <sub>SS</sub> P0		V <sub>SS</sub> is the power supply pin for blocks other than I/O ports (P00 to P27).		
$V_{SS}P2$		V <sub>SS</sub> P0 is the power supply pin for port pins P00 to P07.		
		V <sub>SS</sub> P2 is the power supply pin for port pins P10 to P17 and P20 to P27.		
$V_{DD}$	-	• + power supply pin		
$V_{DD}P0$		• V <sub>DD</sub> is the power supply pin for blocks other than I/O ports (P00 to P27).		
V <sub>DD</sub> P1		V <sub>DD</sub> P0 is the power supply pin for port pins P00 to P07.		
$V_{DD}P2$		V <sub>DD</sub> P1 is the power supply pin for port pins P10 to P17.		
		V <sub>DD</sub> P2 is the power supply pin for port pins P20 to P27.		
		(Notes)		
		<ul> <li>V<sub>DD</sub>P0 must not be set higher than V<sub>DD</sub> I (V<sub>DD</sub>P0≤V<sub>DD</sub>).</li> </ul>		
		<ul> <li>V<sub>DD</sub>P1 must not be set lower than V<sub>DD</sub> (V<sub>DD</sub>P1≥V<sub>DD</sub>).</li> </ul>		
		<ul> <li>V<sub>DD</sub>P2 must not be set lower than V<sub>DD</sub> (V<sub>DD</sub>P2≥V<sub>DD</sub>).</li> </ul>		
Port 0	I/O	8-bit I/O port	Output:	Hi-Z
P00 to P07		I/O specifiable in 1 bit units.	CMOS/Nch-OD	
		CMOS/Nch-open drain specifiable in 1 bit units.	Input: TTL	
		Output voltage variable in 1 port units according to V <sub>DD</sub> P0 voltage.		
Port 1	I/O	• 8-bit I/O port	Output:	Hi-Z
P10 to P17		I/O specifiable in 1 bit units.	CMOS/Nch-OD	
		CMOS/Nch-open drain specifiable in 1 bit units.	Input: TTL	
		Output voltage variable in 1 port units according to V <sub>DD</sub> P1 voltage.		
Port 2	I/O	8-bit I/O port	Output:	Hi-Z
P20 to P27		I/O specifiable in 1 bit units.	CMOS/Nch-OD	
		CMOS/Nch-open drain specifiable in 1 bit units.	Input: TTL	
		<ul> <li>Output voltage variable in 1 port units according to V<sub>DD</sub>P2 voltage.</li> </ul>		

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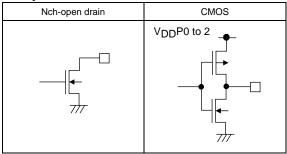
Pin Name	I/O	Description	I/O Type	Reset Time
DIN	- 1	Serial data input pin	Input: TTL	
DOUT	0	Serial data output pin	Output: CMOS	High
CLK		Serial clock input pin	Input: TTL	
	I	Port data is placed on DOUT on the falling edge of this clock.	Schmidt	
		The data from DIN is latched on the negative-to-positive transition of this clock.		
CS	- 1	Chip select input pin	Input: TTL	
		Setting this pin to the low level enables serial data to be input or output.	Schmidt	
RES	- 1	Device's system reset input pin	Input: TTL	
		Setting this pin to the low level initializes the internal control circuit and registers and	Schmidt	
		puts DOUT in the high level and all data port pins (P00 to P27) into the Hi-Z state.		

### Port Output Types and I/O States

The output type and I/O states of the LC709006A's ports can be selected by configuring the data direction register (DDR) and data register (DTR). Port data can be taken into the LC709006A only when DDR is set to 0 (Nch-open drain) and DTR is set to 1 (Nch-Tr OFF). The ports are held high for the other settings of DDR and DTR.

Deat Name	DDD	DTD	Port				
Port Name	DDR	DTR	Output Type	Input	Output		
	0	1	Nch-open drain	Enabled	Hi-Z		
P00 to P07	0	0	Nch-open drain	Disabled (High)	Low		
P10 to P17 P20 to P27	1	1	CMOS	Disabled (High)	High		
1 20 10 1 21	1	0	CMOS	Disabled (High)	Low		

**Port Output Circuit** 



### **Principles of Operation**

The LC709006A accomplishes data transmission and reception to and from the MCU through synchronous serial communication and performs I/O operations on the extended ports in parallel mode. Its communication modes (MCU to LC709006A by serial to parallel conversion and LC709006A to MCU by parallel to serial conversion) include the initial communication modes (modes 0 and 1) in which the LC709006A initializes itself and the data communication mode in which the LC709006A sends and receives port data. The initial communication modes are used for various communication control purposes for the first time in system operation after a power-on or system reset. In these modes, the LC709006A sets up the I/O mode and output type of the ports. The data communication mode is used for communication control after the end of the initial communication modes. In this mode, the LC709006A carries out actual port I/O operations. The port I/O mode and output type settings are stored in the data direction register (DDR). The data output state settings ("High" output, "Hi-Z" output, or "Low" output) are stored in the data register (DTR). The LC709006A's operating modes are summarized below, followed by detailed mode descriptions.

Communication Mode		Description
Mode 0		Sets the output type of all ports to "N-ch-open drain."
Initial communication mode	Mode 1	Sets the I/O direction of the ports and the their output type to CMOS or "Nch-open-drain" on a bit basis.
Data communication mode		Sends and receives port data.

#### (1) Initial communication modes

- Mode 0
- 1) Setting the  $\overline{RES}$  pin to the low level initializes the system, sets the DOUT pin to the high level, and sets the DDR register of all ports to 0 and the DTR register to 1. The output type of the ports is set to Nch-open drain and their I/O state (Nch-Tr=OFF) to the "Hi-Z" (input mode) state.
- 2) When the  $\overline{RES}$  pin is set high (reset) and the  $\overline{CS}$  pin is set and held low for a certain period (TwlCS), the DDR is fixed at 0. Subsequently, the LC709006A is placed in the data communication mode.

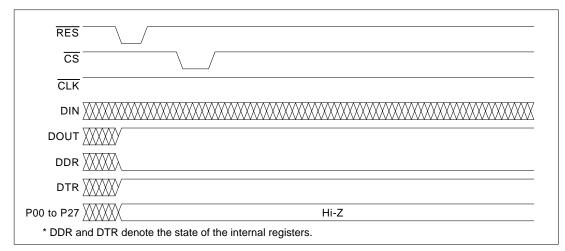


Fig. 1

- Mode 1
- 1) When the RES pin is set to the low level, the LC709006A initializes the system, sets the DOUT pin to the high level, and sets the DDR register of all ports to 0 and the DTR register to 1. The output type of the ports is set to Nch-open drain and their I/O state (Nch-Tr=OFF) to the "Hi-Z" (input mode) state.
- 2) When the RES pins is set high (reset) and the CS pin is set low, the LC709006A gets ready for serial communication.
- 3) The input data at P00 is sent directly to the DOUT pin on the first falling edge of the transmission clock signal CLK. The data at pins P01 to P27 is loaded into the shift register on the rising edge of the next clock.
- 4) Subsequently, the ports' input data, which is loaded into the shift register on the falling edge of CLK, is placed at the DOUT pin sequentially (P00→P07, P20→P27) in synchronization with the falling edges of CLK, starting at port pin P00. In parallel with this operation, when data to be placed at the ports is supplied to the DIN pin sequentially starting at the port pin P00 (P00→P07, P10→P17, P20→P27), it is loaded into the internal shift register in synchronization with the rising edges of CLK.
- 5) When the  $\overline{\text{CS}}$  pin is set high after the rising edge of the 24th clock, the data loaded in the shift register is loaded into the DDR register which determines the I/O mode and output type of the data (serial data is loaded into the DDR register after a reset is effected). Subsequently, the LC709006A controls serial data transmission and reception in the data communication mode.

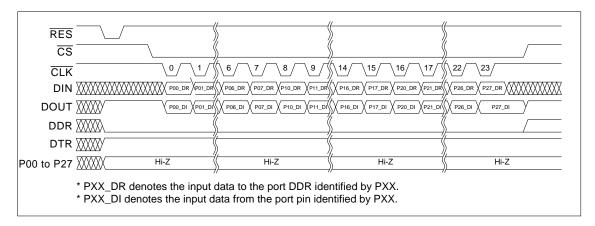


Fig. 2

- (2) Data communication mode
  - 1) When the  $\overline{\text{CS}}$  pin is set low with the  $\overline{\text{RES}}$  pin held high, the LC709006A gets ready for serial communication. (Subsequently, processing in steps 2) and 3) are identical to steps 2) and 3) in paragraph (1)-2).
  - 2) The input data at P00 is sent directly to the DOUT pin on the first falling edge of the CLK signal. Data at pins P01 to P27 is loaded into the shift register on the next rising edge of the clock.
  - 3) Subsequently, the ports' input data, which is loaded into the shift register on the falling edge of CLK, is placed at the DOUT pin sequentially (P00→P07, P10→P17, P20→P27) in synchronization with the falling edges of CLK, starting at port pin P00. In parallel with this operation, when data to be placed at the ports is supplied to the DIN pin sequentially starting at the port pin P00 (P00→P07, P10→P17, P20→P27), it is loaded into the internal shift register in synchronization with the rising edges of CLK.
  - 4) When the CS pin is set high after the rising edge of the 24th clock, the data loaded in the shift register is loaded into the DDR register which determines the output state of the ports and the states of all port pins (P00 to P27) are then changed (output) according to the conditions established in the DDR and DTR registers. Serial data that occurs following the initial communication mode processing is always loaded into the DTR register.

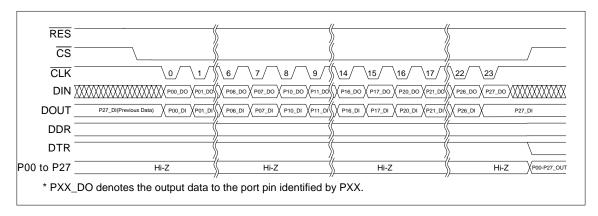


Fig. 3

5) Subsequently, the state of all port pins (P00 to P27) is updated each time the set of steps 1) to 4) described in paragraph (2) are performed.

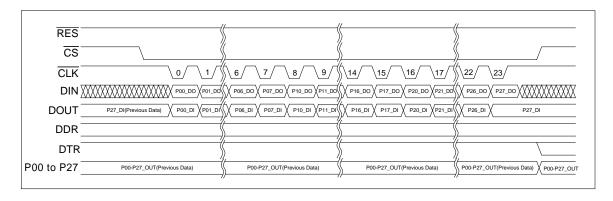


Fig. 4

Note: Connect a Pull-up resister (about  $100k\Omega$ ) to  $\overline{CS}$  using MCU VDD.

#### **Application Examples**

#### (1) Example of a cascade configuration

Two or more LC709006A LSI chips can be cascaded to realize port expansion beyond 24 bits. Port expansion, however, need to be made in units of 24 bits  $\times$  n (n denotes the number of LSI chips).

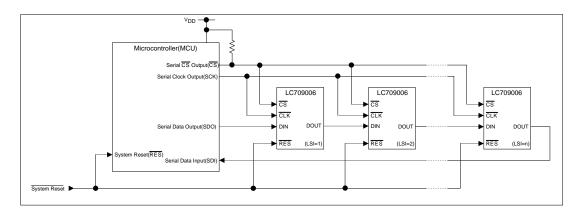


Fig. 5

#### (2) Variable port power level example

When controlling the level of I/O ports according to the power voltage level of the peripheral equipment, the user can connect the output from the power supply of the peripheral equipment directly to the power supply pins for the I/O ports. The LC709006A dispenses with the need to add an external level shifter circuit. Note the following when configuring the LC709006A in this way:

#### Note 5:

- V<sub>DD</sub>P0: The voltage level of V<sub>DD</sub>P0 must not be higher than that of V<sub>DD</sub> (V<sub>DD</sub>P0≤V<sub>DD</sub>).
- VDDP1: The voltage level of VDDP1 must not be lower than that of VDD (VDDP1≥VDD).
- VDDP2: The voltage level of VDDP2 must not be lower than that of VDD (VDDP2≥VDD).
- The input level of all ports (P00 to P27) is dependent on the V<sub>DD</sub> power source; it depends on none of the power sources V<sub>DD</sub>P0 to V<sub>DD</sub>P2.
- \* Be sure to check the electrical characteristics of the LC709006A.

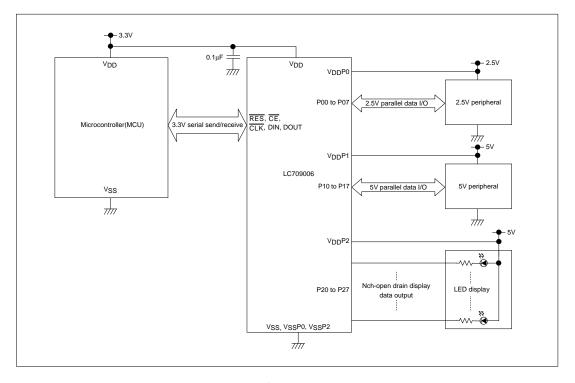


Fig. 6

## Example of Placing Bypass Capacitors between VDD and VSS Terminals

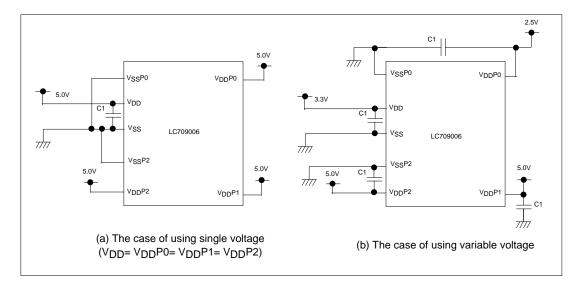


Fig. 7

In the case of using single voltage source as showing in the Fig.7 (a), you must connect a bypass capacitor (C1, about  $0.1\mu F$ ) between  $V_{DD}$  and  $V_{SS}$ . When connecting the capacitor (C1) and  $V_{DD}$ - $V_{SS}$ , use a thick wire, and try to make its length as short as possible: moreover, try to make the impedance of  $V_{DD}$ -C1 and  $V_{SS}$ -C1 equal. In addition, when using several voltage sources as showing in the Fig.7 (b), it is suggested to connect the bypass capacitor to each set of the voltage terminals.

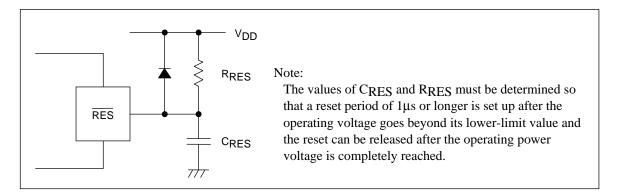


Fig. 8: Reset Circuit

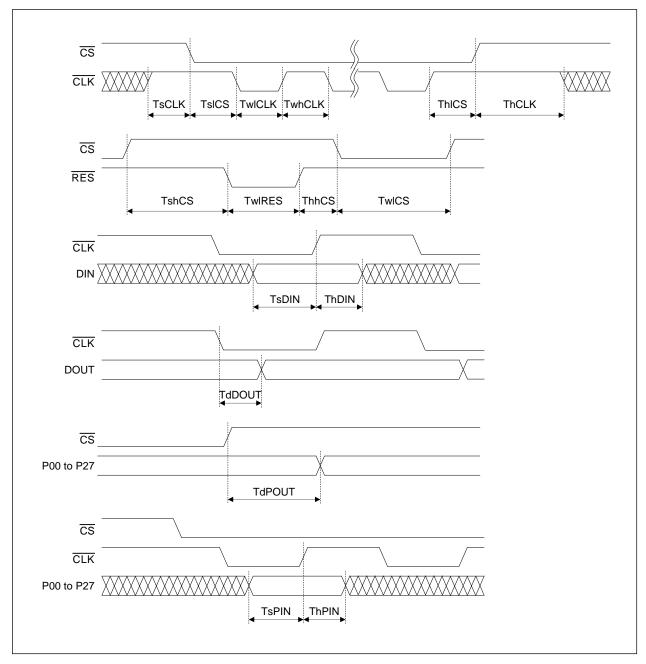


Fig. 9: Serial I/O and Parallel Data I/O Timing Diagram

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